

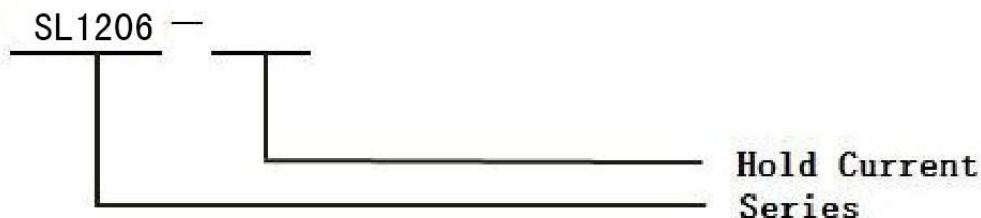
Feature

- Resettable over current and over temperature protection
- Small size of 1206
- Small footprint
- Low resistance
- Fast time-to-trip
- ROHS compliant

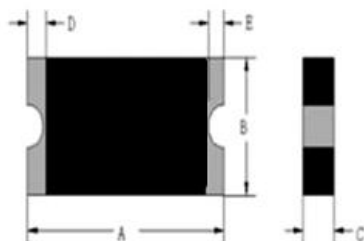
Application

- Computer
- Battery
- Mobile phones
- Industrial controls
- Automotive
- Portable electronics
- Multimedia
- Game machines
- Telephony and broadband

Part Numbering



Product Dimensions in Millimeter



Part Number	A		B		C		D	E
	Min	Max	Min	Max	Min	Max	Min	Min
SL1206110	3.00	3.50	1.50	1.85	0.4	1.0	0.25	0.10
SL1206125	3.00	3.50	1.50	1.85	0.4	1.0	0.25	0.10
SL1206150	3.00	3.50	1.50	1.85	0.5	1.2	0.25	0.10
SL1206175	3.00	3.50	1.50	1.85	0.5	1.2	0.25	0.10
SL1206200	3.00	3.50	1.50	1.85	0.5	1.2	0.25	0.10
SL1206230	3.00	3.50	1.50	1.85	0.5	1.2	0.25	0.10
SL1206260	3.00	3.50	1.50	1.85	0.6	1.3	0.25	0.10
SL1206300	3.00	3.50	1.50	1.85	0.6	1.3	0.25	0.10
SL1206350	3.00	3.50	1.50	1.85	0.6	1.3	0.25	0.10
SL1206380	3.00	3.50	1.50	1.85	0.6	1.5	0.25	0.10
SL1206400	3.00	3.50	1.50	1.85	0.6	1.5	0.25	0.10
SL1206450	3.00	3.50	1.50	1.85	0.6	1.5	0.25	0.10

Electrical Characteristics

Part Number	I(A)		V _{max}	I _{max}	Pd _{typ}	T _{trip}		R _{min}	R _{max}	R _{1max}
	25°C					25°C				
	Hold	Trip	(V)	(A)	(W)	Current(A)	Time(S)	(Ω)	(Ω)	(Ω)
SL1206110	1.10	2.2	6.0	50	1.2	8.0	0.5	0.009	0.015	0.065
SL1206125	1.25	2.5	6.0	50	1.2	8.0	1.0	0.009	0.015	0.060
SL1206150	1.50	3.0	6.0	50	1.2	8.0	5.0	0.006	0.012	0.055
SL1206175	1.75	3.5	6.0	50	1.2	8.0	5.0	0.006	0.012	0.050
SL1206200	2.00	4.0	6.0	50	1.2	8.0	5.0	0.005	0.011	0.045
SL1206230	2.30	4.6	6.0	50	1.2	8.0	5.0	0.005	0.010	0.040
SL1206260	2.60	5.2	6.0	50	1.2	12.0	5.0	0.004	0.009	0.035
SL1206300	3.00	6.0	6.0	50	1.2	12.0	5.0	0.004	0.008	0.030
SL1206350	3.50	7.0	6.0	50	1.2	12.0	5.0	0.002	0.008	0.025
SL1206380	3.80	7.6	6.0	50	1.2	12.0	5.0	0.002	0.007	0.020
SL1206400	4.00	8.0	6.0	50	1.5	16.0	5.0	0.001	0.007	0.018
SL1206450	4.50	9.0	6.0	50	1.5	16.0	5.0	0.001	0.006	0.015

I_H=Hold current: maximum current at which the device will not trip at 25°C or 60°C still air reflow soldering of 260°C for 20 sec.

I_T=Trip current: minimum current at which the device will always trip at 25°C still air reflow soldering of 260°C for 20 sec.

V_{max}=Maximum continuous voltage device can withstand without damage at rated current

I_{max}=Maximum fault current device can withstand without damage at rated voltage.

T_{trip}=Maximum time to trip(s) at assigned current reflow soldering of 260°C for 20 sec.

Pd_{typ}=Typical power dissipation: typical amount of power dissipated by the device when in state air environment.

R_{min}= Minimum resistance of device in initial (un-soldered) state.

R_{max}= Maximum resistance of device in initial (un-soldered) state.

R_{1max}=Maximum resistance of device at 25°C measured one hour after reflow soldering of 260°C for 20sec.

Value specified is determined by using the PWB with 0.030" *1.5oz coppertraces.

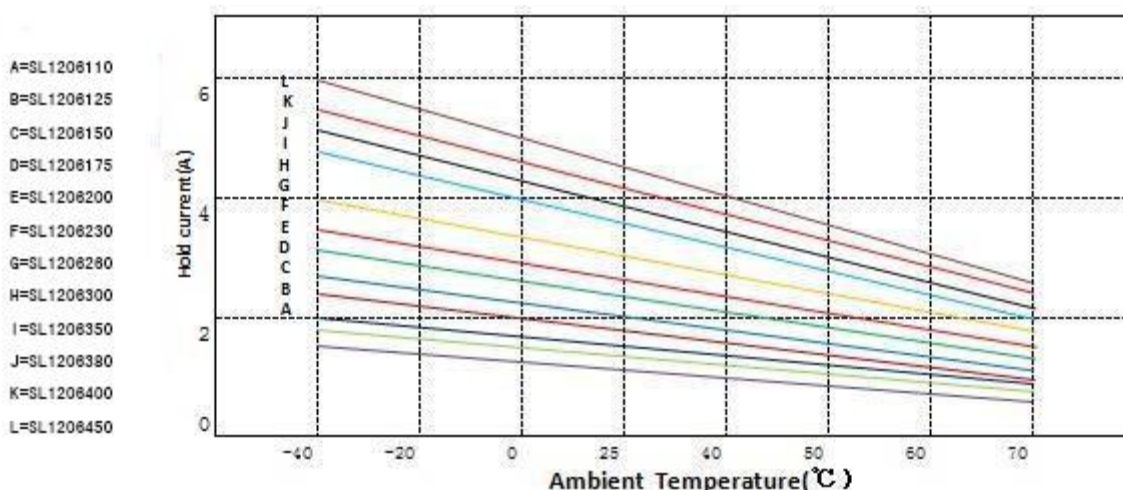
Caution: Operation beyond the specified rating may result in damage and possible arcing and flame.

Environmental Specifications

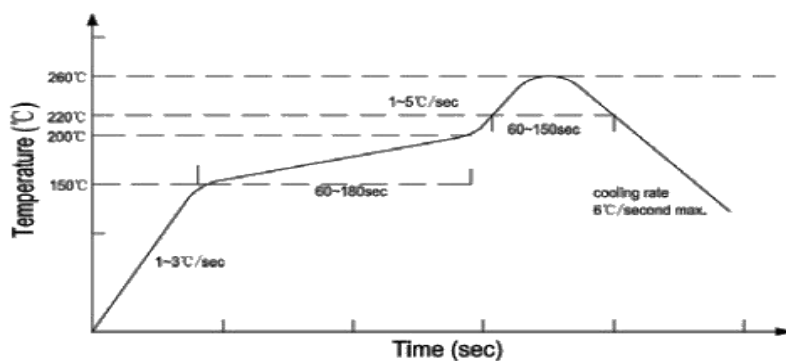
Test	Test Conditions	Resistance Change/ Criteria
Recommended storage conditions	40°C max, 70% R.H. max	± 5%
Passive aging:	85°C, 1000 hours	≤ R1max
Moisture Resistance	85% RH,85°C,1000hrs	≤ R1max
Thermal Shock	MIL-STD-202 Method 107G +85°C /-40°C 20 times	≤ R1max
Vibration	MIL-STD-883C, Method 2007.1, Condition A	± 5%
Solvent Resistance	MIL-STD-202, Method 215	Appearance No change
Moisture Level Sensitivity	J-STD-020C	Level 2a

Thermal Derating [Hold Current (A) at Ambient Temperature (°C)]

Part Number	Maximum Ambient Operating Temperature (°C)							
	-40	-20	0	25	40	50	60	70
SL1206110	1.5	1.3	1.2	1.1	0.9	0.8	0.7	0.6
SL1206125	1.7	1.5	1.4	1.25	1.1	1.0	0.9	0.7
SL1206150	2.0	1.8	1.6	1.5	1.2	1.1	1.0	0.9
SL1206175	2.3	2.0	1.9	1.75	1.4	1.3	1.2	1.0
SL1206200	2.7	2.3	2.2	2.0	1.6	1.5	1.4	1.1
SL1206230	3.1	2.7	2.5	2.3	1.9	1.7	1.6	1.3
SL1206260	3.5	3.0	2.8	2.6	2.1	1.9	1.8	1.5
SL1206300	4.0	3.5	3.2	3.0	2.5	2.2	2.0	1.7
SL1206350	4.7	4.1	3.8	3.5	2.9	2.6	2.4	2.0
SL1206380	5.1	4.4	4.1	3.8	3.1	2.8	2.6	2.2
SL1206400	5.4	4.7	4.3	4.0	3.3	3.0	2.7	2.3
SL1206450	6.0	5.3	4.9	4.5	3.7	3.3	3.1	2.6



Solder Reflow Recommendation



Reflow -curve

Recommended reflow methods: IR, hot air oven, nitrogen oven
 Devices can be cleaned using standard industry methods and solvents.

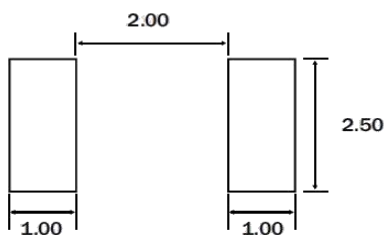
NOTE:

If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

Caution: Operation beyond the rated voltage or current may result in rupture electrical arcing or flame

Packaging Quantity and Marking

Recommended Pad Layout (mm.)



Operation beyond the maximum ratings or improper use may result in device damage and possible electrical arcing and flame. The devices are intended for protection against occasional over-current or over temperature fault conditions and should not be used when repeated fault conditions or prolonged trip events are anticipated. Device performance can be impacted negatively if devices are handled in a manner inconsistent with recommended electronic, thermal, and mechanical procedures for electronic components.

Contact information

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Rev. letter		Date	
Design	Check	Audit	Approve



CAUTION: